

P-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (mΩ)(Typ.)	I _D (A) ^a	Q _g (Typ.)			
- 60	7.5 at V _{GS} = - 10 V	- 90	120 nC			
- 00	9.5 at $V_{GS} = -4.5 \text{ V}$	- 90				

FEATURES

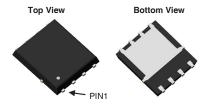
- DT-Trench Power MOSFET
- 100 % R_q and UIS Tested
- Low RDS(ON)
- · High Current Capability

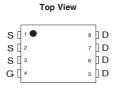


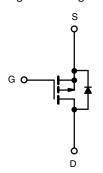
APPLICATIONS

- General Automotive Applications
- · Battery protection charge/discharge

DFN5X6-8L Pin Configuration







P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER	SYMBOL	LIMIT	UNIT			
Drain-Source Voltage	V _{DS}	- 60	V			
Gate-Source Voltage	V _{GS}	± 20	V			
Continuous Drain Current /T 450 °C\2	T _C = 25 °C	,	- 90			
Continuous Drain Current (T _J = 150 °C) ^a	T _C = 100 °C	I _D	- 54	Α		
Pulsed Drain Current ^b	I _{DM}	- 360				
Single Avalanche Energy	E _{AS}	245	mJ			
Manipular Danier Dispiration(T _C = 25 °C	D	110	W		
Maximum Power Dissipation ^c	T _C = 100 °C	P _D	44	VV		
Operating Junction and Storage Temperature Ra	T _J , T _{sta}	- 55 to +150	°C			

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	LIMIT	UNIT		
Junction-to-Ambient (PCB Mount) ^d	R _{thJA}	40	°C/W		
Junction-to-Case (Drain)	R _{thJC}	1.13			

Notes

- a. Calculated continuous current based on maximum allowablejunction temperature.
- b. Repetitive rating; pulse width limited by max. junction temperature.
- c. Pd is based on max. junction temperature, using junction-case thermal resistance.
- d. The value of R_{0JA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper,in a still air environment with Ta=25 °C.



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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static				•			
Drain-Source Breakdown Voltage	V_{DS}	V _{GS} = 0, I _D = - 250 μA	- 60			V	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = -250 \mu A$	- 1		- 3	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zara Cata Valtaga Drain Current		V _{DS} = - 60 V, V _{GS} = 0 V			- 1	^	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 48 V, V _{GS} = 0 V, T _J = 55 °C			- 50	- 50 μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -5 V$, $V_{GS} = -10 V$	- 90			Α	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 10 V, I _D = - 15 A		7.5	9.2		
Drain-Source On-State Resistance	1 (DS(on)	V _{GS} = - 4.5 V, I _D = - 15 A		9.5	14	mΩ	
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 5 V, I _D = - 15 A		40		S	
Dynamic ^b				•	•		
Input Capacitance	C _{iss}			4890		pF	
Output Capacitance	C _{oss}	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		930			
Reverse Transfer Capacitance	C _{rss}	7		5			
Total Gate Charge	Qg			120			
Gate-Source Charge	Q_{gs}	$V_{DS} = -30 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -15 \text{ A}$		21		nC	
Gate-Drain Charge	Q_{gd}	7		32			
Gate Resistance	R _g	f = 1 MHz		8.5		Ω	
Turn-On Delay Time	t _{d(on)}			18			
Rise Time	t _r	V_{DD} = - 30 V, R $_{L}$ =1.5 Ω		20		- ns	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ -15 A, $V_{GEN} =$ - 10 V, R $_g = 3\Omega$		90			
Fall Time	t _f	1		45			
Drain-Source Body Diode Characterist	ics						
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			- 90	Α	
Pulse Diode Forward Current	I _{SM}				- 360		
Body Diode Voltage	V_{SD}	I _S = - 1 A			- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}	- I _F = -15 A, dI/dt = 100 A/μs, Τ _J = 25 °C		35		ns	
Body Diode Reverse Recovery Charge	Q_{rr}	1 _F = 10 Λ, αι/αι = 100 Λ/μ3, 1 _J = 23 °C		180		nC	

Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

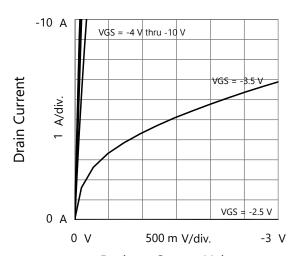
a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

b. Guaranteed by design, not subject to production testing.

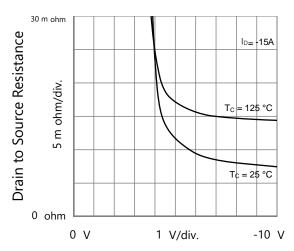




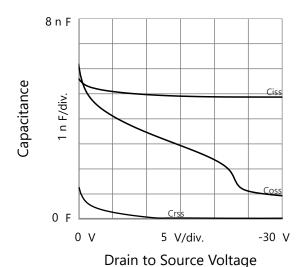
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



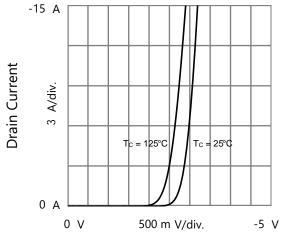
Drain to Source Voltage Output Characteristics



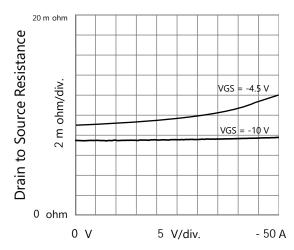
Gate to Source Voltage
Drain to Source Resistance vs. Gate to Source Voltage



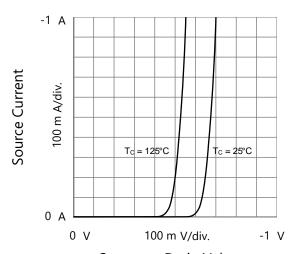
Capacitances



Gate to Source Voltage Transfer Characteristics



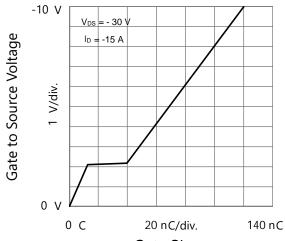
Drain Current
Drain to Source Resistance vs. Drain Current



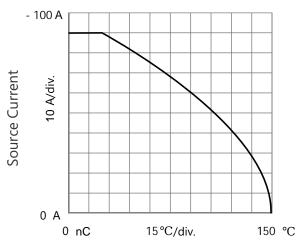
Source to Drain Voltage Body Diode Forward Characteristics



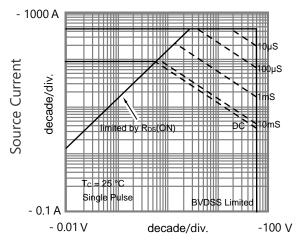
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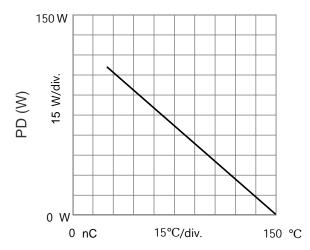
Gate Charge
Gate to Source Voltage vs. GateCharge



 $T_C \textbf{- Case Temperature}_{\text{Current Derating}}$

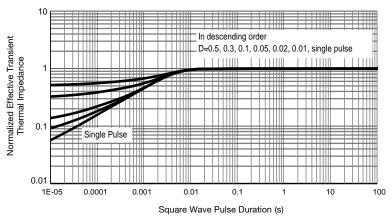


Source to Drain Voltage Safe Operating Area, Junction-to-Ambient



T_C - Case Temperature

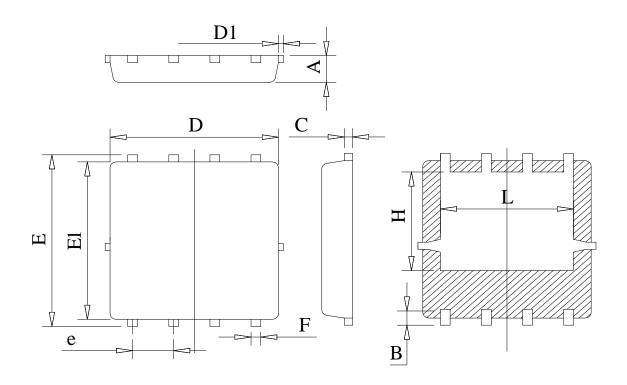
Power Derating



Normalized Thermal Transient Impedance, Junction-to-Case



DFN5X6-8L PACKAGE OUTLINE



COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

Unit: mm

Symbol	Min	Тур	Max
A	0.78	0.95	1.12
В	0.45	0.58	0.78
С	0.18	0.254	0.36
D	4.70	5.20	5.45
D1			0.18
Е	5.85	6.05	6.25
E1	5.38	5.55	5.98
e	1.15	1.27	1.40
F	0.18	0.30	0.52
Н	3.25	3.47	3.70
L	3.75	4.00	4.25

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